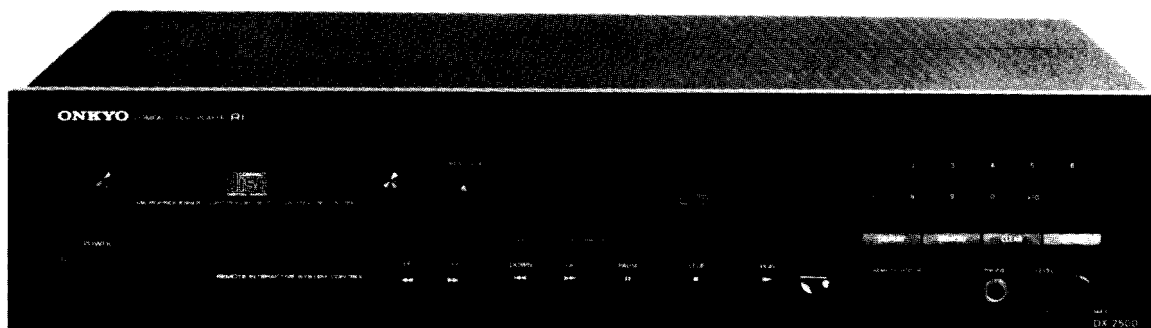


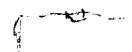
ONKYO® SERVICE MANUAL

COMPACT DISC PLAYER MODEL DX-2500



Black model

BUDN, BUD	120V AC, 60 Hz
BUG -	220V AC, 50Hz
BUU	110/120/220/240V AC, 50/60Hz
BUQA, BUQB	240V AC, 50 Hz



SAFETY-RELATED COMPONENT WARNING!!

COMPONENTS IDENTIFIED BY MARK Δ ON THE SCHEMATIC DIAGRAM AND IN THE PARTS LIST ARE CRITICAL FOR RISK OF FIRE AND ELECTRIC SHOCK. REPLACE THESE COMPONENTS WITH ONKYO PARTS WHOSE PART NUMBERS APPEAR AS SHOWN IN THIS MANUAL.

MAKE LEAKAGE-CURRENT OR RESISTANCE MEASUREMENTS TO DETERMINE THAT EXPOSED PARTS ARE ACCEPTABLY INSULATED FROM THE SUPPLY CIRCUIT BEFORE RETURNING THE APPLIANCE TO THE CUSTOMER.

SPECIFICATIONS

Signal readout system:	Optical non-contact
Reading rotation:	About 500~200 r.p.m. (constant linear velocity)
Linear velocity:	1.2~1.4m/s
Error correction system:	Cross interleave readsolomon code
Decoded bits:	16 bits linear
Sampling frequency:	88.2kHz (two-times oversampling)
Number of channels:	2 (stereo)
Frequency response:	2Hz~20kHz
Total harmonic distortion:	0.004% (at 1kHz)
Dynamic range:	93dB
Signal to noise ratio:	96dB
Channel separation:	90dB (at 1kHz)
Wow and Flutter:	Below threshold of measurability
Power consumption:	16 watts
Output level:	2 volts r.m.s.
Dimensions (W x H x D):	435 x 98 x 361mm 17-1/8" x 3-7/8" x 14-1/4"
Weight:	4.8kg, 10.6 lbs

Specifications are subject to change without notice.

ONKYO
AUDIO COMPONENTS

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SERVICE PROCEDURES

1. Regarding the lock for transport protection

For the protection of the laser and optical parts during transport, a lock is provided on the bottom surface of the machine. When using the machine, turn the transport lock lever 180° counterclockwise to release the optical pickup. If the lock is not turned completely, the section at the beginning of the recording will be interrupted. When this symptom occurs, check the position of the lock lever.

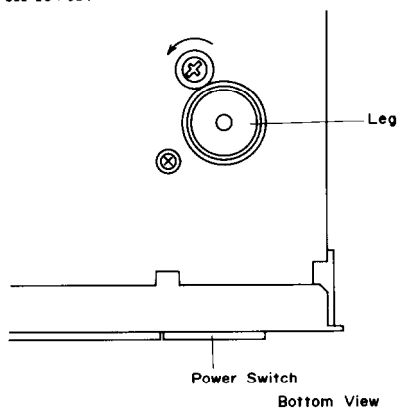


Fig. 1

2. Procedures for replacement of flat packaged ICs

1. Tools to be used:

- (1) **Soldering iron** Grounded soldering iron or soldering iron with leak resistance of 10 Mohms or more.

Form of soldering iron's tip:

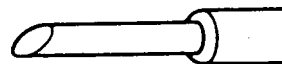


Fig. 2

- (2) **Magnifying glass** ... for checking of finished works
 (3) **Tweezers** for handling of IC and forming of leads
 (4) **Grounding ring** Countermeasure for electrostatic breakdown
 (5) **Nipper** for removing defective IC
 (6) **Small brush** for application of flux
 (7) **Enamel line**

2. Work Procedures:

(1) Remove the defective IC

Cut all leads of the defective IC one by one using a nipper and remove the IC.

1. An enamel line has been pierced between the legs of the flat package IC.
2. Use a soldering iron to unsolder the legs one at a time.
3. Repeat the procedure of 1 and 2 above for the 3 sides only.

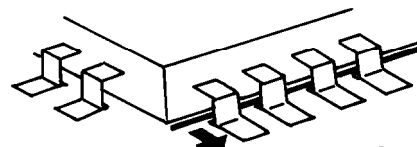


Fig. 3-a

While holding the soldering against the enamel line, pull in the direction of the arrow.

(2) Clean the pattern surface of the PC board.

Get rid of the remaining leads and solder.

(3) Check and from the leads of the new flat packaged IC to be installed.

From every lead on the new IC using a pair of tweezers, so that all of them are aligned neatly without being risen, twisted or inclined toward one side. Especially the rising portion of every lead must be formed with greatest care.

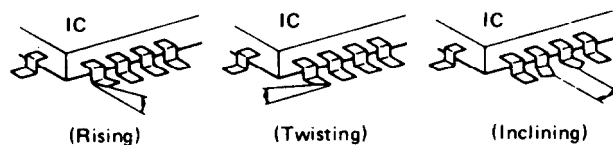


Fig. 3-b

(4) Apply flux to the PC board.

Apply flux to the pattern surface of the PC board which has been cleaned, as shown in the illustration. The area to be applied with flux is the portion of about 2.5mm in width where the IC's leads are to be soldered.

Be careful to apply minimum amount of flux required so as not to smear it on unwanted areas.

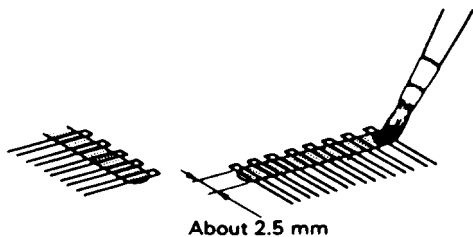


Fig. 4

(5) Temporarily tighten the IC

Carefully align the pattern and IC's leads, so that the IC will be temporarily tightened to the pattern on the four leads at the corners. At this time, soldering is required, but no need to apply soldering material.

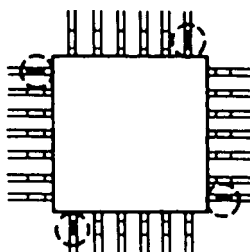


Fig. 5

(6) Apply flux to IC's leads

Apply flux to the areas of IC's leads where soldering is to be performed. Be careful not to smear flux on the root portion of any lead or the body of IC.

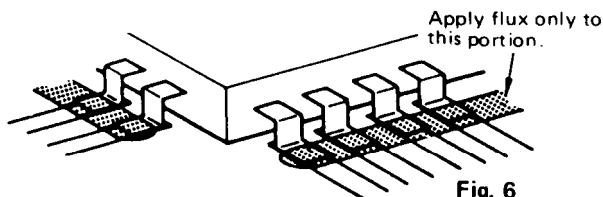


Fig. 6

(7) Soldering

While attaching the tip of the soldering iron to the soldering point as shown in the illustration, feed 2–5mm of soldering wire. Then, slowly move the iron in the direction indicated by the arrow in the illustration, so that the leads will be soldered to the pattern. Move the iron in the rate of approximately 1cm in 5sec. Proceed with your work while confirming a clean fillet of solder is formed on each lead, subsequent to the melting of flux.

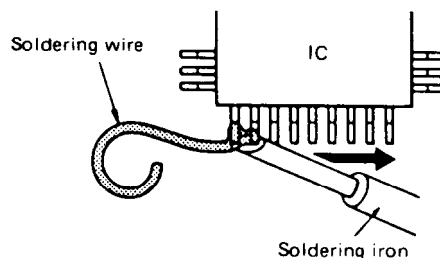


Fig. 7

CAUTION

- 1) If you move the iron too quickly, loose soldering is likely to result.
- 2) Be especially careful when soldering the first lead where loose soldering is most liable to be formed.

(8) Check the results

When soldering of all leads is finished, check the soldered portion on every lead with a magnifying glass. A tester must not be used or checking of any soldered position

3. Safety-check out (U.S.A. model)

After correcting the original service problem, perform the following safety check before releasing the set to the customer:

Connect the insulating-resistance tester between the plug of power supply cable and chassis.

Specifications: more than 10Mohm at 500V.

PROTECTION OF EYES FROM LASER BEAM DURING SERVICING

This set employs a laser. Therefore, be sure to follow carefully the instructions below when servicing.

WARNING!!

WHEN SERVICING, DO NOT APPROACH THE LASER EXIT WITH THE EYE TOO CLOSELY. IN CASE IT IS NECESSARY TO CONFIRM LASER BEAM EMISSION, BE SURE TO OBSERVE FROM A DISTANCE OF MORE THAN 30cm FROM THE SURFACE OF THE OBJECTIVE LENS ON THE OPTICAL PICK-UP BLOCK.

Laser Diode Properties

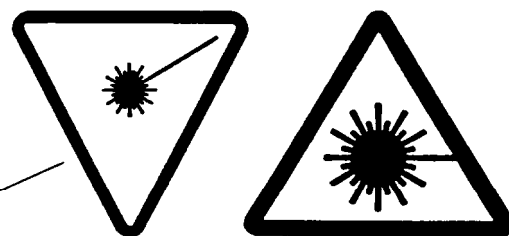
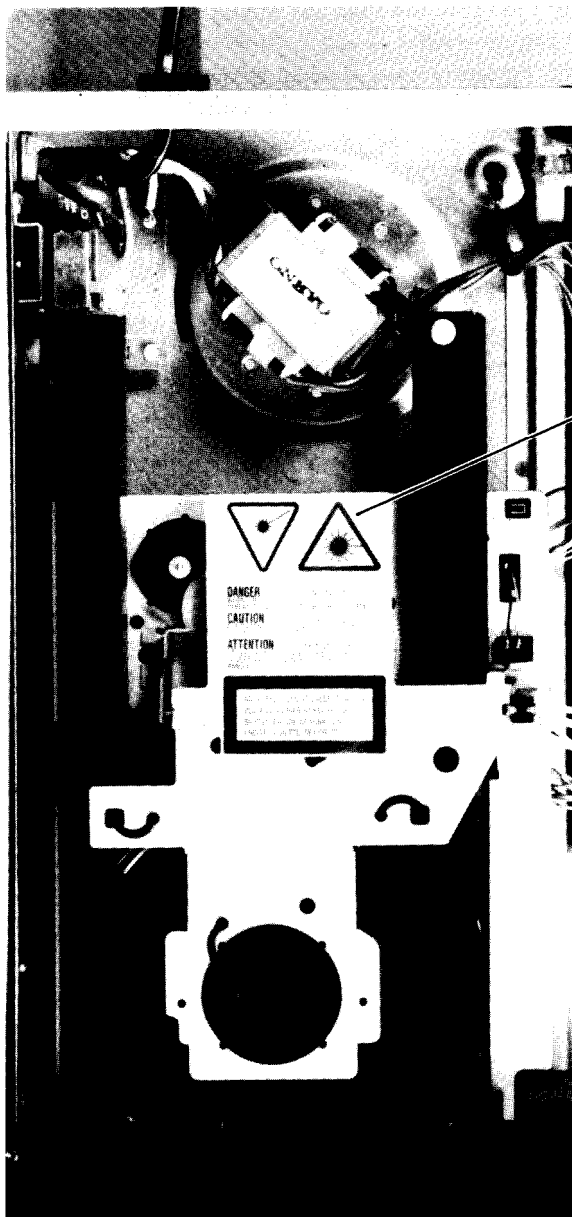
- Material: GaAS/GaAlAs
- Wavelength: 780nm
- Emission Duration: continuous
- Laser output: max. 0.5mW*

*This output is the value measured at a distance about 1.8mm from the objective lens surface on the Optical Pick-up Block.

LASER WARNING LABEL

The label shown below are affixed.

1. Warning label



DANGER —INVISIBLE LASER RADIATION WHEN OPEN AND INTERLOCK FAILED OR DEFEATED. AVOID DIRECT EXPOSURE TO BEAM.

CAUTION —HAZARDOUS LASER AND ELECTROMAGNETIC RADIATION WHEN OPEN AND INTERLOCK DEFEATED.

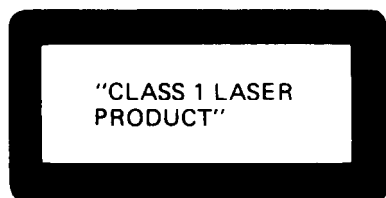
ATTENTION —RAYONNEMENT LASER ET ELECTROMAGNETIQUE DANGEREUX SI OUVERT AVEC L'ECLenchement DE SECURITE ANNULE.
SN29360911

ADVARSEL: USYNLIG LASERSTRÅLING
VED ÅBNING, NÅR SIKKERHEDSAF-
BRYDER ER UDE AF FUNKTION.
UNDGÅ UDSÆTTELSE FOR STRÅLING.

Photo 1

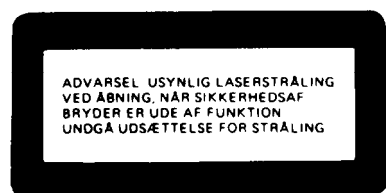
2. **Certification label** (Only UD:120V model)
This label is located on the back panel.
3. **Class 1 label** (Other models)
This label is located on the back panel.

ADVARSEL



Denne mærkning er anbragt på apparatets højre side og indikerer, at apparatet arbejder med laserstråler af klasse 1, hvilket betyder, at der anvendes laserstråler af svageste klasse, og at man ikke på apparatets yderside kan blive udsat for utilladelig kraftig straling.

APPARATET BØR KUN ÅBNES AF FAGFOLK MED SÆRLIGT KENDSKAB TIL APPARATER MED LASERSTRÅLER!



Indvendigt i apparatet er anbragt den her gengivne advarselmærkning, som advarer imod at foretage sådanne indgreb i apparatet, at man kan komme til at udsætte sig for laserstråling.

VAROITUS! Laite sisältää laserdiodin, joka lähettää (näkymätöntä) silmille vaarallista lasersäteilyä.

Fig. 8

NOTE ON COMPACT DISC

• Holding Compact Discs

Hold Compact Discs by the edges so that you do not touch the surface of disc. Remember that the side of the disc with the "rainbow" reflection is the side containing the audio information.

Do not attach tape or paper to the label side of the disc and always be careful not to leave fingerprints on the side that is played.

• Storing Compact Discs

Store Compact Discs in a location protected from direct sunlight, high heat and humidity and extremely high and low temperatures. Discs should never be left in the trunk or interior of an automobile in the sun since the temperature can become very high in such a closed environment.

Always store Compact Discs in the holders in which they were sold. Never leave a disc in the player's disc holder for a long period of time.

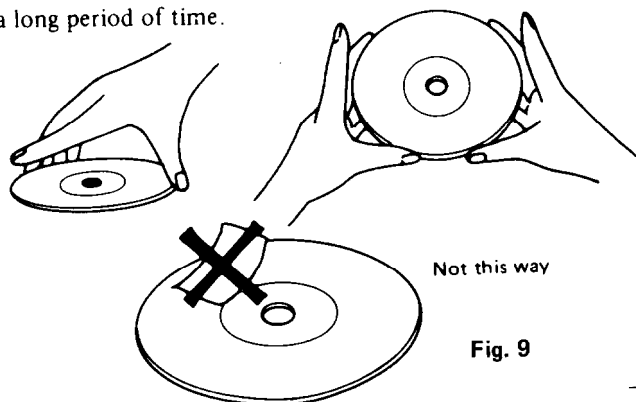


Fig. 9

• Cleaning Compact Discs

Before playing a disc wipe off the playing surface with a soft cloth to remove dust and other soil. Wipe the surface in straight lines from the center of the disc outward, not in a circular motion as you would with a phonograph record.

Do not use benzene, chemical cleansers or phonograph record cleaning solutions to clean Compact Discs. Also avoid static electricity prevention solutions since they can damage the surface of Compact Discs.



Fig. 10

Problems Caused by Dew

Dew can form inside a Compact player when it is brought from a cold environment into a warm room, when a room is rapidly heated and if a player is left in a humid environment.

This dew can prevent the laser pickup from reading the data contained in the pits in the disc surface. If the player does not operate properly because of dew, remove the disc and leave the player's power switch on for about one hour to remove all moisture.

CAUTION ON REPLACEMENT OF PICK-UP

The laser diode in the optical pick-up block is so sensitive to static electricity, surge current and etc. that the components are liable to be broken down or its reliability remarkably deteriorated.

During repair, carefully take the following precautions. (The following precautions are included in the service parts).

PRECAUTIONS

1. Ground for the work-desk.

Place a conductive sheet such as a sheet of copper (with impedance lower than $10^6 \Omega$) on the work-desk and place the set on the conductive sheet so that the chassis.

2. Grounding for the test equipment and tools.

Test equipments and toolings should be grounded in order that their ground level is the same the ground of the power source.

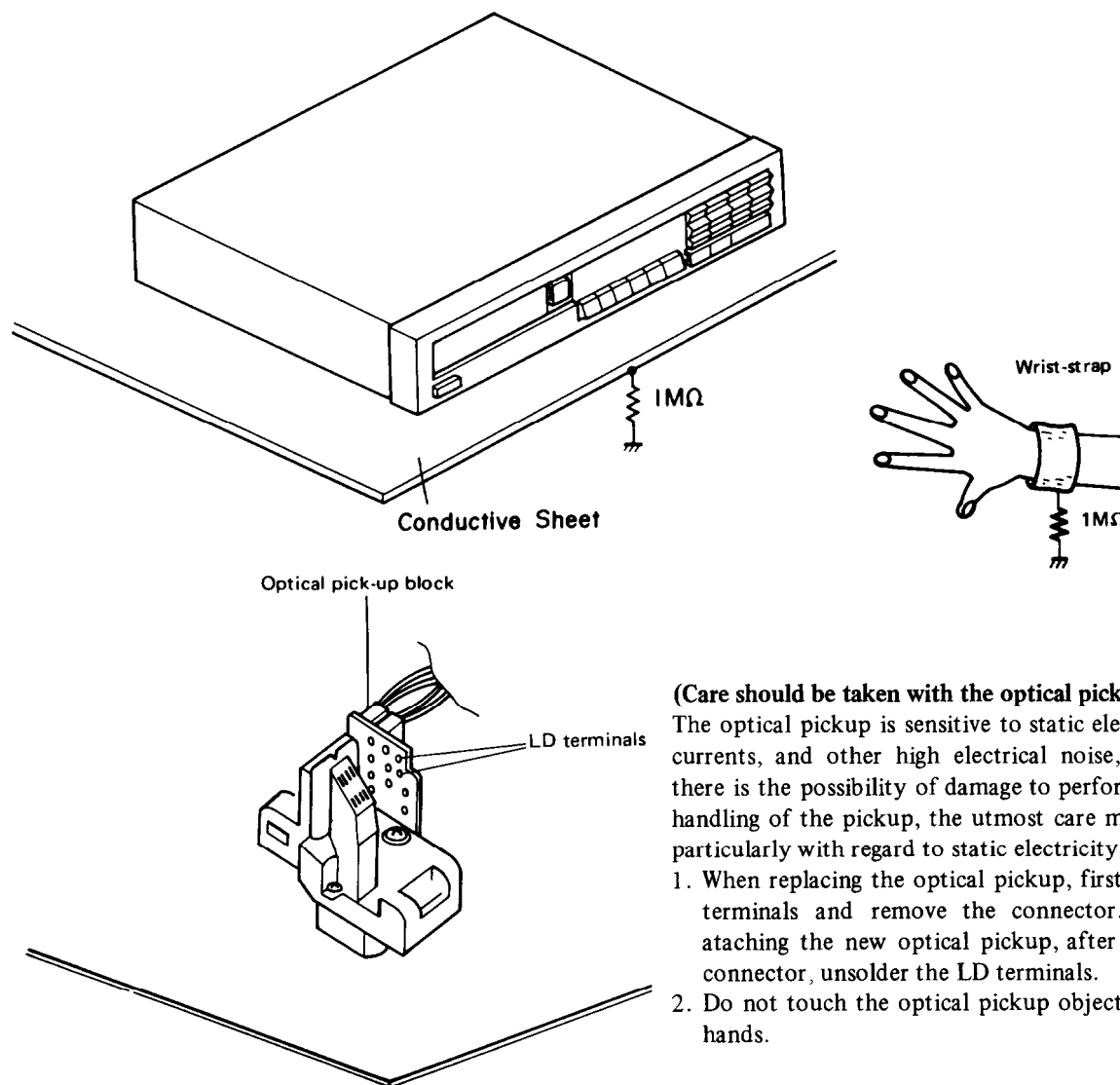
3. Grounding for the human body.

Be sure to put on a wrist-strap for grounding whose other end is grounded.

Be particularly careful when the workers wear synthetic fiber clothes, or air is dry.

4. Select a soldering iron that permits no leakage and have the tip of the iron well-grounded.

5. Do not check the laser diode terminals with the probe of a circuit tester or oscilloscope.



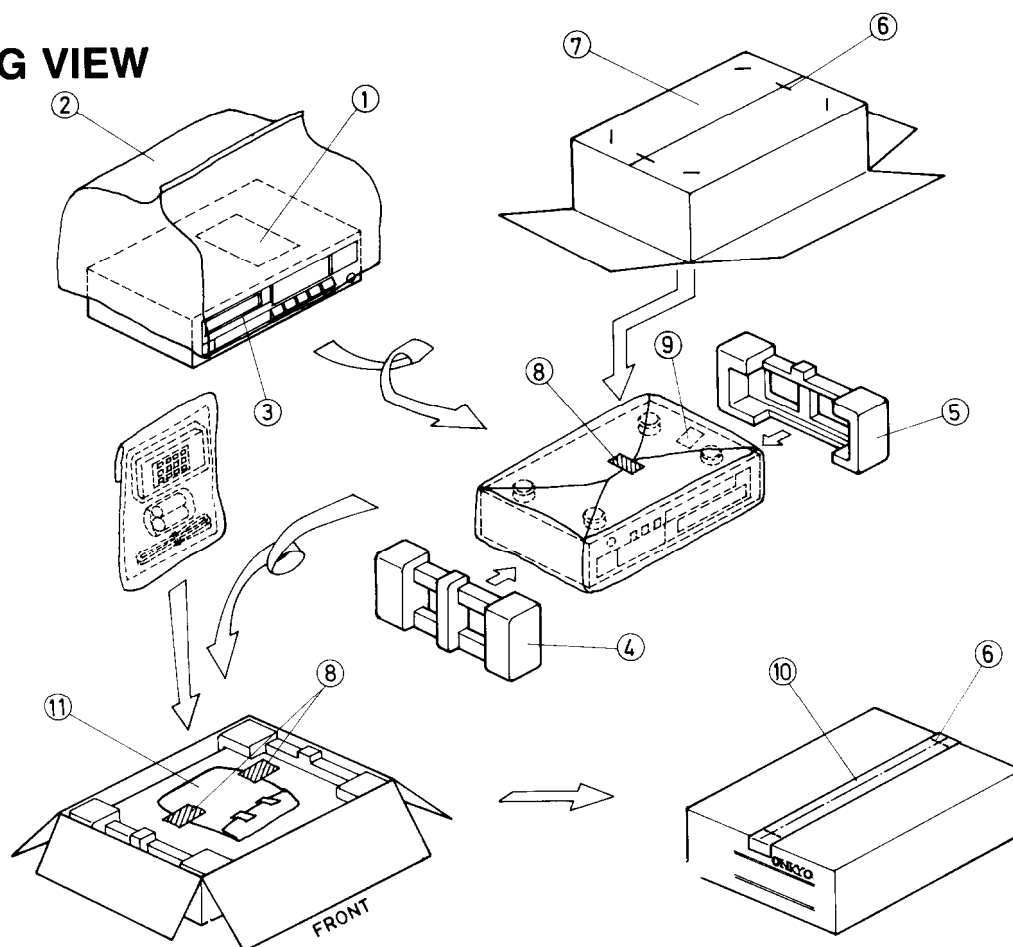
(Care should be taken with the optical pickup.)

The optical pickup is sensitive to static electricity, surge currents, and other high electrical noise, and because there is the possibility of damage to performance, in the handling of the pickup, the utmost care must be taken, particularly with regard to static electricity.

1. When replacing the optical pickup, first short the LD terminals and remove the connector. Also, when attaching the new optical pickup, after attaching the connector, unsolder the LD terminals.
2. Do not touch the optical pickup object lens with the hands.

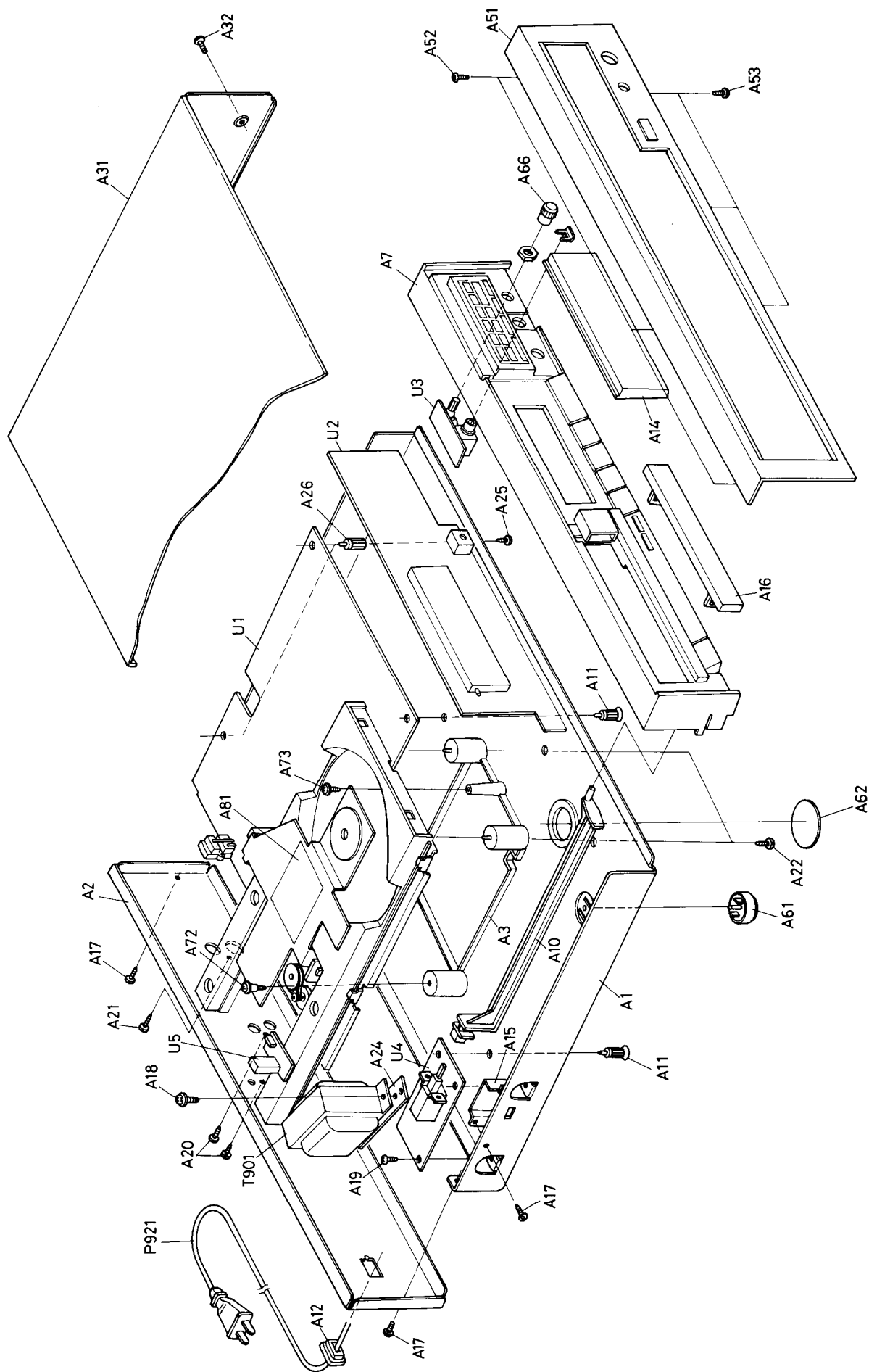
Fig 11

PACKING VIEW



REF.NO.	PART NO.	DESCRIPTION	REF. NO.	PART NO.	DESCRIPTION
1	29361011	Caution sheet			
2	29100036A	550 × 850mm, Poly-vinyl bag			
3	29095505	Protection sheet			
4	29091238	Pad R			
5	29091237	Pad L			
6	282301	Sealing hook			
7	29051678	Master carton box			
8	261504	50 × 30mm, Adhesive tape			
9	29361027	Caution label			
10	260012	50 × 500mm, Damp-Proof paper			
11		Accessory bag ass'y			
		-120V models-			
	2010098A	Connection cord			
	29341293	Instruction manual			
	24140022	RC-120C, Remote control unit			
	3010054	UM-3, Two batteries			
	29100006A	350 × 250mm, Poly-vinyl bag			
	2010169	Connection cord for remote control			
	29365019	Warranty card (Only U.S. model)			
	29358002E	Service station list (Only U.S. model)			
		-220V models-			
	2010098A	Connection cord			
	29341294	Instruction manual			
	29341295	Instruction manual, Italian			
	24140022	RC-120C, Remote control unit			
	3010054	UM-3, Two batteries			
	29100006A	350 × 250mm, Poly-vinyl bag			
	2010169	Connection cord for remote control			
		-240V models-			
	2010098A	Connection cord			
	29341231	Instruction manual			
	29341294	RC-120C, Remote control unit			
	3010054	UM-3, Two batteries			
	29100006A	350 × 250mm, Poly-vinyl bag			
	2010169	Connection cord for remote control			

EXPLODED VIEW



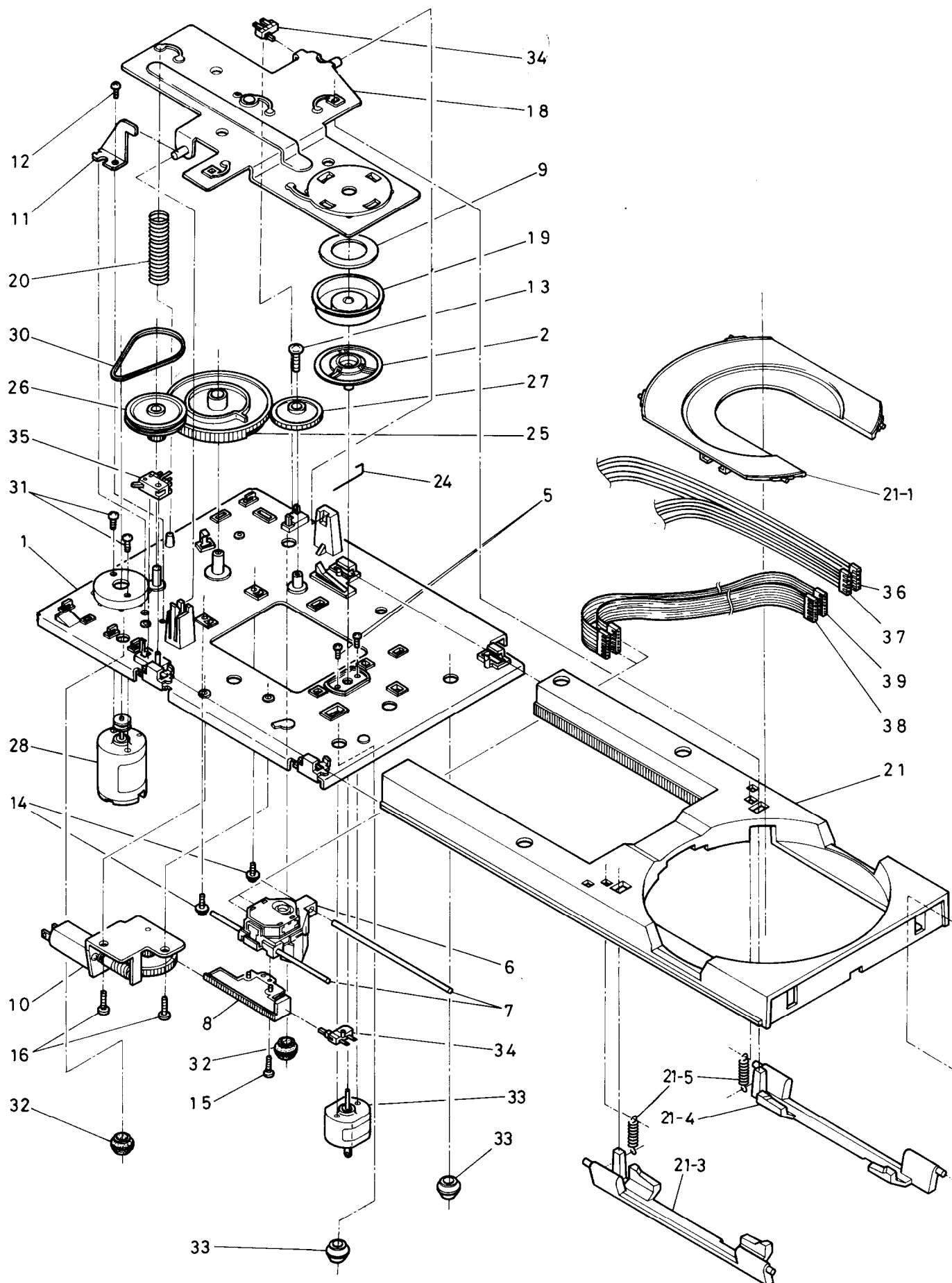
EXPLODED VIEW – PARTS LIST

REF. NO.	PART NO.	DESCRIPTION	REF. NO.	PART NO.	DESCRIPTION
A1	27100159A	Chassis	U2	1H040569-1	NADIS-3269-1,Display circuit pc board ass'y
A2	27121092	Back panel <D>	U3	1H040570-1	NAAF-3270-1,Headphone amplifier pc board ass'y
	27121093	Back panel <G>	U4	1H040572-1	NAPS-3272-1,Power supply circuit pc board ass'y
	27121095	Back panel <U>	U5	1H040571-1	NAETC-3271-1,Terminal pc board ass'y
	27121125	Back panel <Q>	W1	260208	Binder
A3	27190612A	Holder, mechanism			
A7	27110414A	Front bracket ass'y			
A10	27273096A	Joint,power			
A11	27190524	Holder			
A12	27300750	Strainrelief			
A14	28191462A	Clear plate			
A15	27141125	Bracket S			
A16	27210940A	Tray panel			
A17	834430068	3TTS + 6B(BC),Tapping screw			
A18	830440109	4TTC + 10C(BC), Tapping screw			
A19	831130088	3TTW + 8B,Tapping screw			
A20	834430108	3TTS + 10B(BC),Tapping screw			
A21	834230108	3TTS + 10B(Ni), Nickel screw			
A22	833430080	3TTP + 8P,Tapping screw			
A23	831430100	3TTW + 10P(BC),Tapping screw			
A24	27270214A	Spacer			
A25	833435082	3.5STP + 8BQ(BC),Tapping screw			
A26	27190063	KGTS-8T,Holder			
A31	28184385	Top cover			
A32	834430088	3TTS + 8B(BC),Tapping screw			
A51	1H041121	Front panel ass'y			
A52	833430080	3TTP + 8P(BC),Tapping screw			
A53	834430068	3TTS + 6B(BC),Tapping screw			
A61	27175130	Leg			
A62	27270255	Spacer			
A66	28323325	Knob VOLUME			
A72	801364	Special screw			
A73	801410	Special screw			
A81	29360911	Label, LASER			
A91	27141090A	Bracket U <U>			
A92	834430088	3TTS + 8B(BC),Tapping screw <U>			
P921	253112A	AS-UC-4#18,Power supply cord <D>			
	253148 or	AS-CEE 250V 2.5A,			
	253150	Power supply cord <G/U>			
	253118	AS-SAA,Power supply cord <Q>			
S902	25065168	HXW0131-01-060, Voltage selector switch <U>			
T901	2300291	NPT-991D,Power transformer <D>			
	2300292	NPT-991G,Power transformer <G>			
	2300294	NPT-991ADGQ,Power transformer <U>			
	2300293	NPT-991Q, Power transformer <Q>			
U1	1H040586-5	NAAR-3086-5,Main circuit pc board ass'y <D/W>			
	1H040586-5A	NAAR-3086-5a, Main circuit pc board ass'y <G/Q>			

NOTE: <D>:Only 120V model
<G>:Only 220V model
<U>:Only Universal model
<Q>:Only 240V model

NOTE: THE COMPONENTS IDENTIFIED BY MARK  ARE CRITICAL FOR RISK OF FIRE AND ELECTRIC SHOCK. REPLACE ONLY WITH PART NUMBER SPECIFIED.

MECHANISM EXPLODED VIEW



PARTS LIST

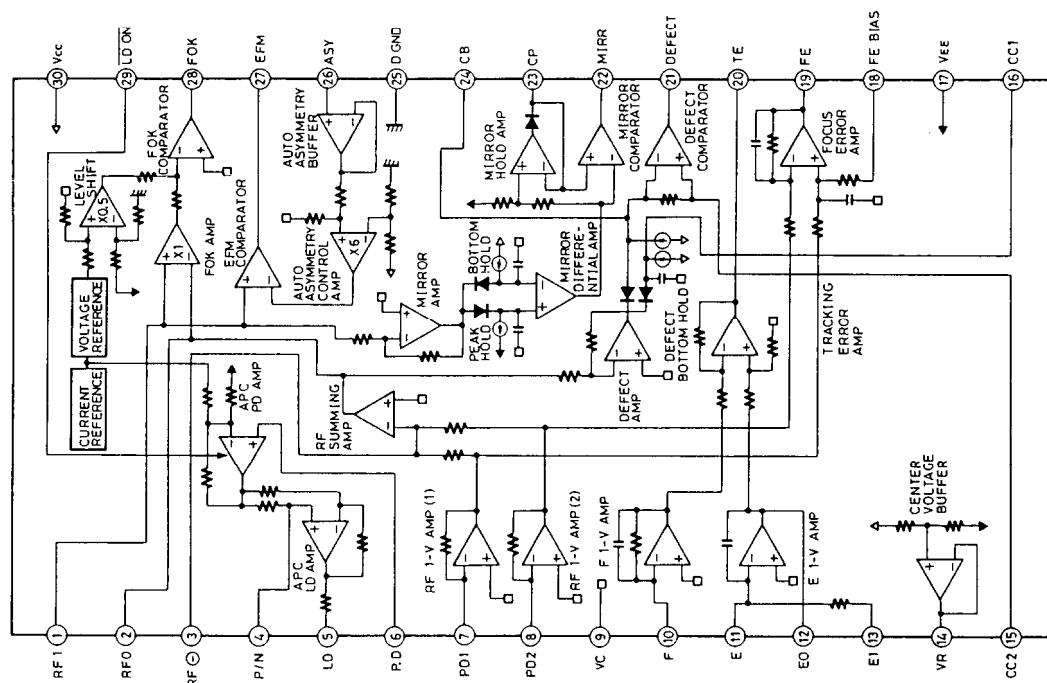
REF.NO.	PART NO.	DESCRIPTION
1	27100140F	Mechanism chassis
2	1H025903	Turntable ass'y
3	24502213A	Spindle motor
5	82142003	2P + 3F(BC), Pan head screw
6	24110001	KSS-152A, Optical pick-up
7	27260222	Shaft
8	27300939	Rack
9	27270234	Spacer
10	1H025902	Slide motor ass'y
11	27141230	Bracket, holder
12	834430068	3TTS + 6B(BC), Tapping screw
13	838426088	2.6TTB + 8B(BC), Tapping screw
14	831430100	3TTW + 10P(BC), Tapping screw
15	833420068	2TTF + 6B(BC), Tapping screw
16	833430080	3TTP + 8P(BC), Tapping screw
17	82142003	2P + 3F(BC), Pan head screw
18	27300946F	Arm ass'y
19	27300848A	Cap CH
20	27180341A	Spring
21	27301112B	Disc tray
21-1	27301113	Disc plate
21-3	27301114	Disc lifter L
21-4	27301115	Disc lifter R
21-5	27180400	Spring
24	27180405	Spring
25	27300942B	Cam gear
26	27300943	Pulley gear
27	27300944	Gear
28	1H025901	Tray motor ass'y
30	27301079	Rubber belt
31	82143004	3P + 4FN(BC), Pan head screw
32	27301107	Cushion rubber
33	27300854A	Cushion rubber
34	25065321	NMS-1113, Microswitch (S-002/S-003)
35	25065322	NMS-1214, Microswitch (S-001)
36	2000733B	NSAS-6P689, Socket ass'y, Tray motor
37	2000734B	NSAS-6P690, Socket ass'y, Spindle motor
38	2000753	NSAS-8P709, Socket ass'y, White
39	2000581D	NSAS-8P537, Socket ass'y, Red
40	27180408	Spring (Back left side)

Lubrication: FLOIL.....G902S(Part No. 260447)

Place.....Between Arm and Cam gear

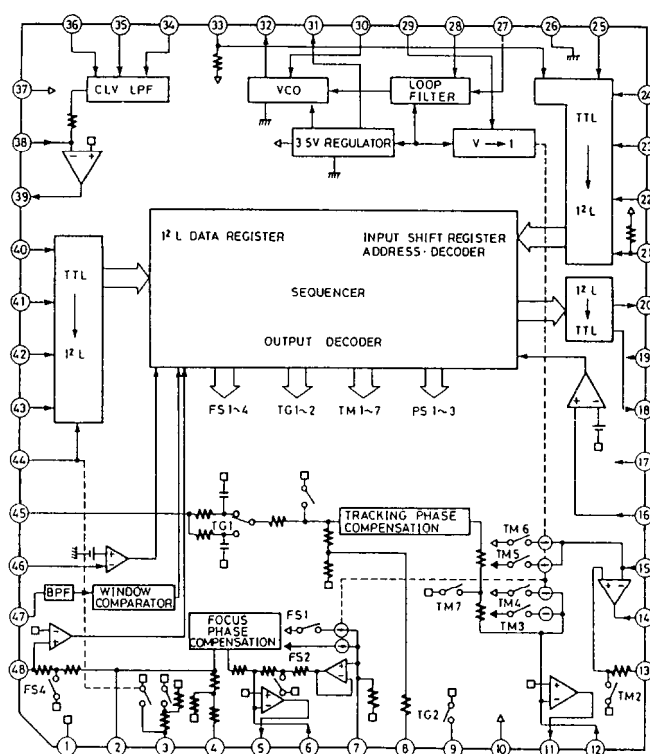
IC BLOCK DIAGRAM AND DESCRIPTIONS

CXA1081M (RF Amp)



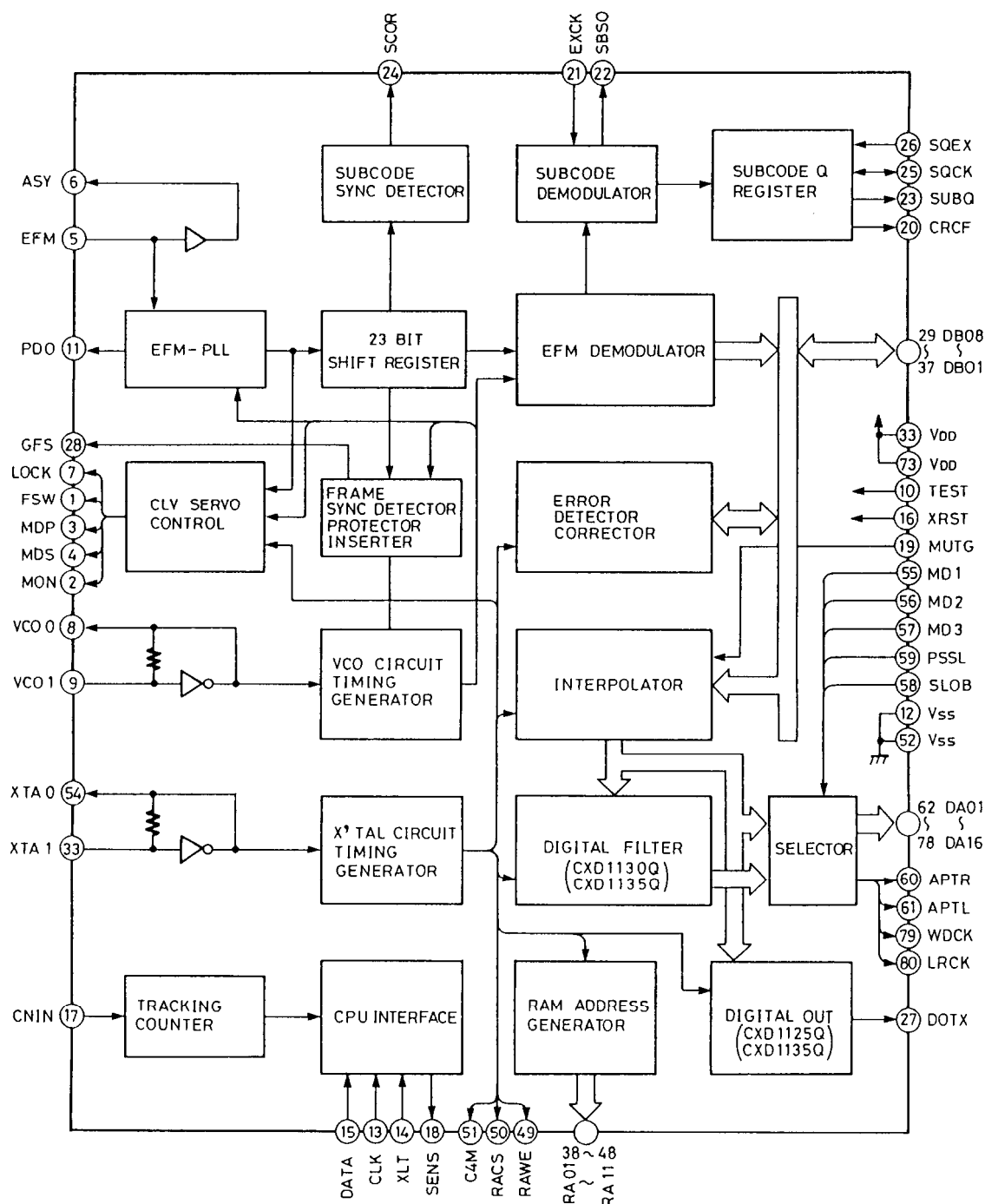
Pin No.	Symbol	Function	Pin No.	Symbol	Function
1	RF I	Input terminal of output signal of RF summing amplifier via the coupling capacitor	16	CC1	Defect bottom hold output terminal
2	RFO	Output terminal of RF summing amplifier	17	V _{EE}	Negative power supply terminal
3	RF-	Input terminal of RF summing amplifier feedback	18	FE BIAS	Non-inversion bias terminal of focus error amplifier CMR adjustment of focus error amplifier
4	P/N	Switching terminal of P-SUB/N-SUB of LD (laser diode)	19	FE	Output terminal of focus error amplifier
5	LD	Output terminal of APC LD amplifier	20	TE	Output terminal of tracking error amplifier
6	PD	Input terminal of APC PD (Pin diode) amplifier	21	DEFECT	Output terminal of defect comparator
7	PD1	Inversion input terminal of RF I-V amplifier (1) Connect to A+C of PIN diodes.	22	MIRR	Output terminal of mirror comparator
8	PD2	Inversion input terminal of RF I-V amplifier (2) Connect to B+D of PIN diodes.	23	CP	Connection terminal of capacitor for mirror hold Non-inversion input of mirror comparator
9	VC	Connect to GND.	24	CB	Connection terminal of capacitor for defect bottom hold
10	F	Inversion input terminal of F I-V amplifier Connect to F of PIN diode.	25	DGND	Connect to GND
11	E	Inversion input terminal of E I-V amplifier Connect to E of PIN diode.	26	ASY	Auto asymmetry control input terminal
12	E0	Output terminal of E I-V amplifier	27	EFM	Output terminal of EFM comparator
13	E1	Feedback input terminal of E I-V amplifier Gain adjustment of E I-V amplifier	28	FOK	Output terminal of FOK comparator
14	VR	DC voltage output terminal of (V _{CC} + V _{EE})/2	29	LD ON	ON/OFF switching terminal of laser diode
15	CC2	Input terminal from defect bottom hold output signal via the coupling capacitor	30	V _{CC}	Positive power supply

CXA1082AQ (Servo Signal Processor)

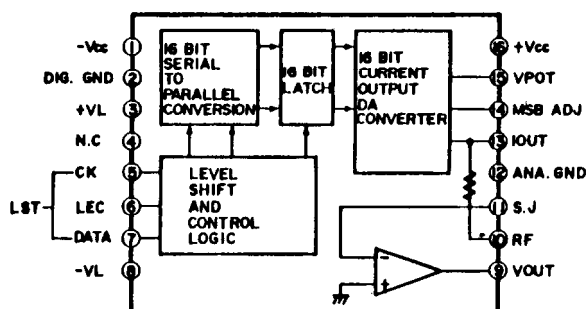


Pin No.	Symbol	Function	Pin No.	Symbol	Function
2	FGD	Insert the capacitor between this terminal and pin 3 when drop the high frequency gain of focus servo	28	PDI	Input terminal of phase comparator output PDO
3	FS3	Switching terminal of high frequency gain of focus servo	21	DIRCT	Input terminals for microcomputer and interface
4	FLB	Time constant switching terminal when raise the low frequency gain of focus servo	22	XRST	
5	FEO	Operation amplifier output terminals for power transistor drive	23	DATA	
11	TAO		24	XTL	
14	SLO		25	CLK	
39	SPDLO		33	LOCK	
6	FE-	Inversion input terminal of focus amplifier	29	ISET	Flow the current to decide the focus search, track jump, and kick height
7	SRCH	Time constant terminal to make the focus search waveform	30	VCOP	VCO free run frequency is proportion to resistor value between pins 30 and 31
8	TGU	Time constant terminal for high frequency gain switching of tracking	32	C864	VCO (8.64MHz) output terminal
9	TG2	Time constant terminal for high frequency gain switching of tracking	34	MDP	Connection terminal to terminal MDP of CXD1135Q
12	TA-	Inversion input terminal of tracking amplifier	35	MON	Connection terminal to terminal MON of CXD1135Q
13	SL+	Non-inversion input terminal of sled amplifier	36	FSW	LPF time constant terminal of CLV servo error signal
15	SL-	Inversion input terminal of sled amplifier	38	SPDL-	Inversion input terminal of spindle drive amplifier
16	SSTOP	Limit switch ON/OFF detector signal terminal for disc innermost position detector	40	WDCK	Input terminals for microcomputer and interface
17	FSET	Terminal of peak of phase compensation of focus tracking and of setting of LPF	41	FOK	
18	SENS	Output terminals for microcomputer and interface	42	MIRR	
20	C.OUT		44	DFCT	
27	BW	Time constant terminal of loop filter	45	TE	Tracking error signal input terminal
			46	TZC	Tracking zero cross comparator input terminal
			47	ATSC	Window comparator input terminal for ATSC detection
			48	FE	Focus error signal input terminal

CXD1135Q (Digital Signal Processor)

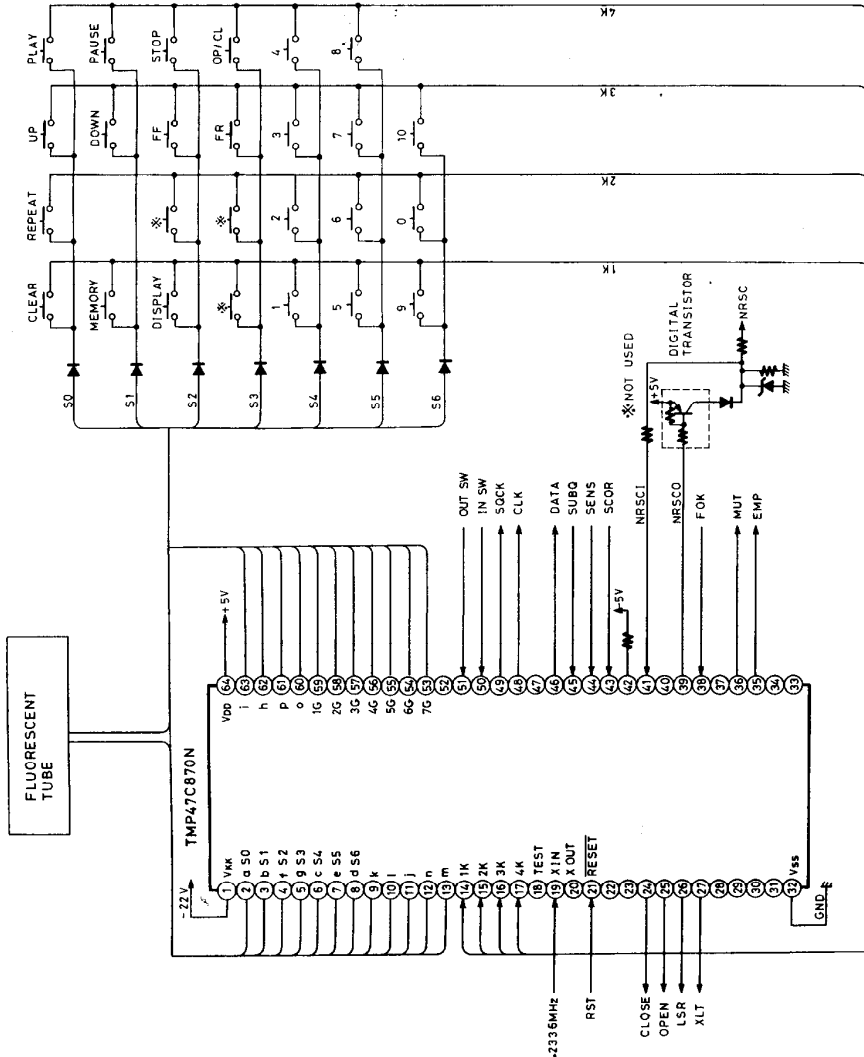


PCM-56P-L(D/A Converter)



1	-Vcc	Analog power supply(-)	9	VOUT	Output
2	DIG. GND	Digital ground	10	RF	Feedback register
3	+VL	Logic voltage (+)	11	SJ	Operation amplifier input
4	NC	Not used	12	ANA. GND	Analog ground
5	CK	Clock input	13	IOUT	Current output
6	LEC	Latch enable input	14	MSB ADJ	MSB adjustment terminal
7	DATA	Data input	15	VPOT	Meter terminal
8	-VL	Logic voltage (-)	16	+Vcc	Analog power supply (+)

Pin No.	Symbol	Function	Pin No.	Symbol	Function
1	FSW	Time constant switching output terminal of output filter of spindle motor	49	RAWE	Write enable signal output to external RAM
2	MON	ON/OFF control output terminal of spindle motor	50	RACS	Chip selector signal output to external RAM
3	MDP	Drive output terminal of spindle motor. Rough control when mode CLV-S and phase control when mode CLV-P	51	C4M	Divider output of crystal. f=4.2336MHz
4	MDS	Drive output terminal of spindle motor. Speed control when mode CLV-P	52	Vss	Ground
5	EFM	EFM signal input terminal from RF amplifier	53	XTAI	Input terminal of crystal oscillator
6	ASY	Output terminal to control the slice level of EFM signal	54	XTAO	Output terminal of crystal oscillator
7	LOCK	GFS sampling terminal	55	MD1	Mode switching input terminals
8	VCOO	VCO output terminal. 8.6436MHz when lock to EFM signal	57	MD3	
9	VCOI	VCO input terminal	58	SLOB	Code switching input of audio data output.
10	TEST	0V	59	PSSL	Mode switching input of audio data output. Serial output at low level. Parallel output at high level
11	PDO	Phase comparator output terminal of EFM signal and VCO/2	60	APTR	Control output for aperture correction. High level when Rch.
12	Vss	Ground	61	APTL	Control output for aperture correction. High level when Lch.
13	CLK	Serial data transmitter clock input terminal from microcomputer	62	DA01	DA01 (LSB of parallel sound output) output when PSSL = H. C1F1 output when PSSL = L
14	XLT	Latch input terminal from microcomputer	63	DA02	DA02 output when PSSL = H. C1F2 output when PSSL = L.
15	DATA	Serial data input terminal from microcomputer	64	DA03	DA03 output when PSSL = H. C2F1 output when PSSL = L.
16	XRST	System rest input terminal. Reset at low level.	65	DA04	DA04 output when PSSL = H. C2F2 output when PSSL = L.
17	CNIN	Tracking pulse input terminal	66	DA05	DA05 output when PSSL = H. C2FL output when PSSL = L.
18	SENS	Inner condition output terminal correspond to address	67	DA06	DA06 output when PSSL = H. C2PO output when PSSL = L.
19	MUTG	Muting input terminal	68	DA07	DA07 output when PSSL = H. RFCK output when PSSL = L.
20	CRCF	CRC check output terminal of subcode Q	69	DA08	DA08 output when PSSL = H. WFCK output when PSSL = L.
21	EXCK	Clock input terminal for serial output of subcode	70	DA09	DA09 output when PSSL = H. PLCK output when PSSL = L.
22	SBSO	Serial output terminal of subcode	71	DA10	DA10 output when PSSL = H. UGFS output when PSSL = L.
23	SUBQ	Subcode Q output terminal	72	DA11	DA11 output when PSSL = H. GTOP output when PSSL = L.
24	SCOR	Subcode sink S0 + S1 output terminal	73	VDD	Power supply (5V)
25	SQCK	Clock terminal to read the subcode Q	74	DA12	DA12 output when PSSL = H. RAOV output when PSSL = L.
26	SQEX	Selector input terminal of SQCK	75	DA13	DA13 output when PSSL = H. C4LR output when PSSL = L.
27	DOTX	Digital output terminal	76	DA14	DA14 output when PSSL = H. C210 output when PSSL = L.
28	GFS	Indicator output of lock condition of frame sync	77	DA15	DA15 output when PSSL = H. C210 output when PSSL = L.
29	DB08	Data terminals of external RAM	78	DA16	DA16 (MSB of parallel sound output) output when PSSL = H. DATA output when PSSL = L
32	DB05		79	WDCK	Strobe signal output. 176.4kHz when DF is on. 88.2kHz when DF is off.
33	VDD	+5V	80	LRCK	Strobe signal output. 88.2kHz when DF is on. 44.1kHz when DF is off.
34	DB04	Data terminals of external RAM			
37	DB01				
38	RA01	Address output terminals of external RAM			
48	RA11				



Pin No.	Terminal	I/O	Description
1	V _{kk}		Power supply terminal(21V)
2~13	a~g, j~m	O	Fluorescent tube segment drive output and key matrix output signal(a~g)
14~17	1K~4K	I	Input terminal from operation keies.
19	C4M	I	Clock input terminal from X'tal(4.2336 MHz)
21	RST	I	Reset input terminal
24	CLOSE	O	L level during the tray closes.
25	OPEN	O	L level during the tray opens.
26	LSR	O	L level when the laser turns on.
27	XLT	O	Interface of signal processor IC.
32	GND		Ground terminal
35	EMPHASIS	O	Emphasis switching signal output. Active H
36	MUTING	O	Muting switching signal output. Active H
38	FOK	I	Focus OK input terminal. Focus OK at high level.
39	NRSC OUT	O	Remote control signal output terminal.
41	NRSC IN	I	Remote control signal input terminal.
43	SCOR	I	Subcode synchronizing signal input terminal.
44	SENS	I	Interface of signal processor IC.
45	SUBQ	I	Sub code Q input terminal.
46	DATA	O	Serial data signal output terminal
48	CLK	O	Serial data transmission clock
49	SOCK	I/O	Read clock of sub code Q
50	IN SW	I	L level at the arm down.
51	OUT SW	I	L level at the tray open.
53~59	1G~7G	O	Output terminals of grid of fluorescent tube
60~63	h, i, o, p	O	Fluorescent tube segment output terminals.
64	V _{DD}		Power supply terminal.

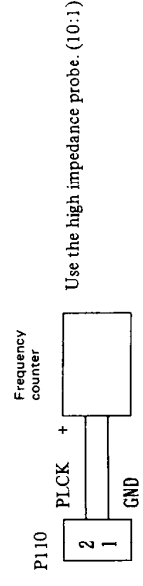
ADJUSTMENT PROCEDURES

Instruments required

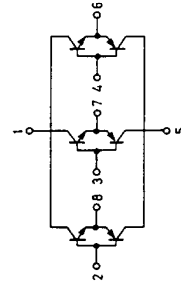
Dual trace oscilloscope, Frequency counter, CR oscillator, Test disc (SONY YEDS-18), AC voltmeter, Sockets P109 & P110 (Part No. 25050089) P108 (Part No. 25050138)

1. VCO frequency adjustment

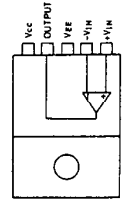
Connect the frequency counter to terminal P110. Turn the power switch to ON.(No load the disc). Adjust R147 until the frequency counter reading becomes $4322 \pm 5\text{kHz}$. After adjustment, disconnect the frequency counter.



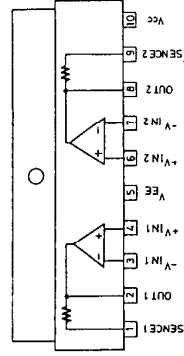
STA341M-L (Transistor Array)



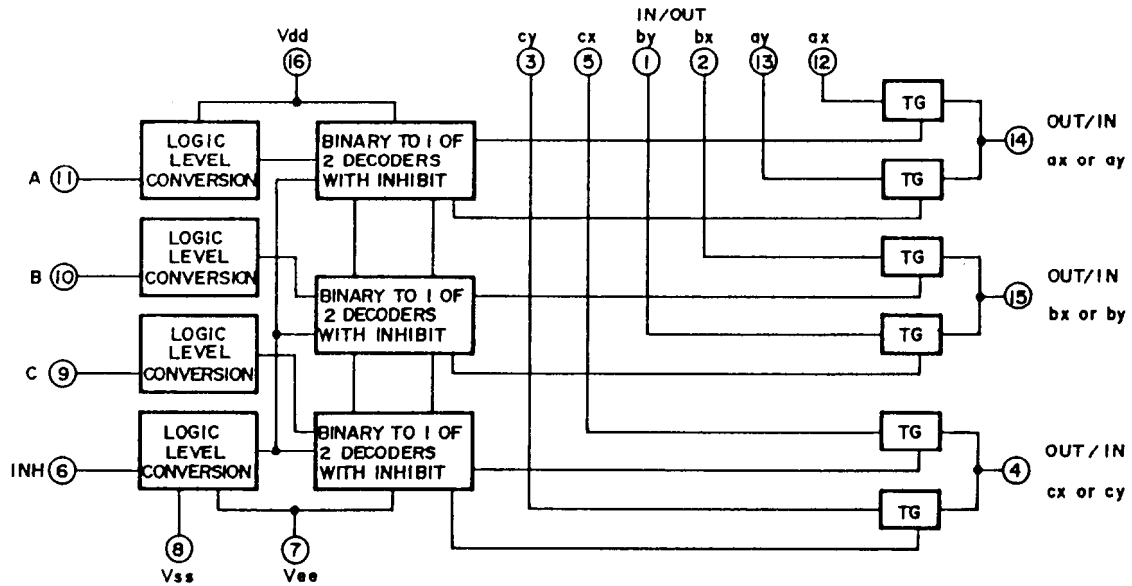
LA6500 (Power OP Amp)



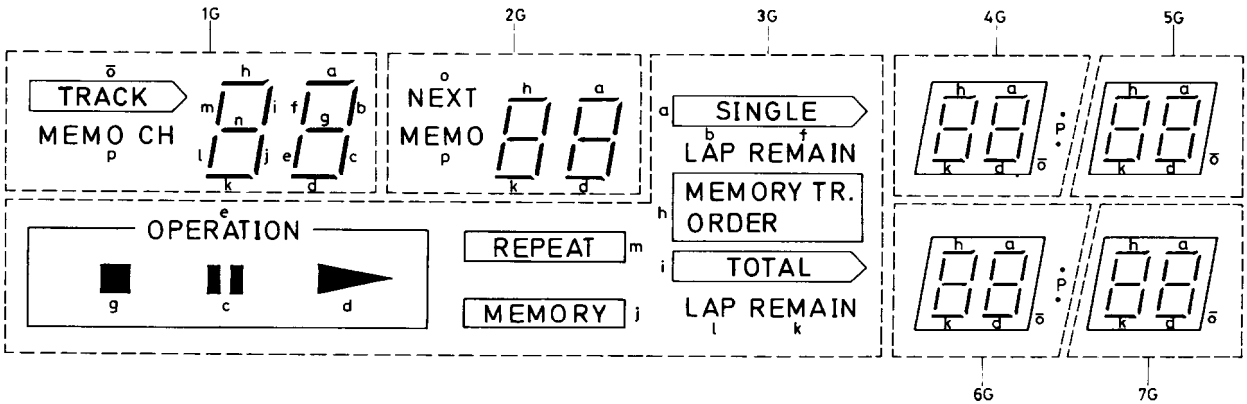
LA6510 (Power OP Amp)



BU4053B(Analog Switch)



7- BT-93GK(Fluorecent indicator tube)



PIN CONNECTION

PIN No.	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
CONNECTION	F	F	N	N	7	6	5	4	3	2	1	o	p	h	i	N	N	N
PIN No.	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	34	35	
CONNECTION	N	m	n	j	l	k	d	e	c	g	f	b	a	N	N	F	F	

2. Focus offset adjustment

Load the test disc (YEDS-18) on the tray and play back the track 2.

Connect the oscilloscope to terminal P109.

Adjust R110 until a clear trace of waveform pattern as shown photo 1 appear on the oscilloscope.

(When the amount of jitter is broad, set R110 to mechanical center)

After adjustment, disconnect the oscilloscope.

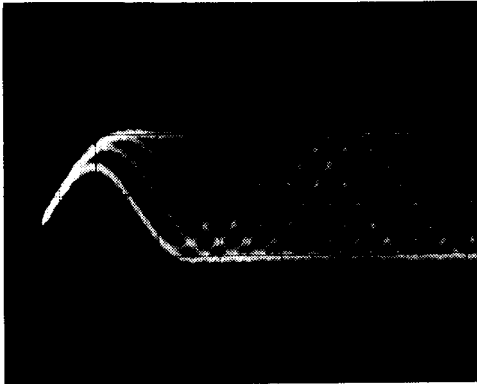
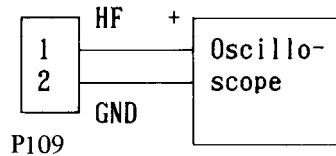


Photo 1



Oscilloscope range
Vertical: 0.2V/div
Horizontal: 0.2μS/div
Use the high impedance probe.

3. Tracking offset adjustment

Play back the track 2 of test disc.

Turn R125 to minimum position(counter-clockwise).

Connect the oscilloscope between pin 3(TR) of P108 and pin 2(GND) of P109.

Adjust R108 until the center of tracking error signal on the oscilloscope becomes GND level.

Turn R125 to mechanical center.

After adjustment, disconnect the oscilloscope.

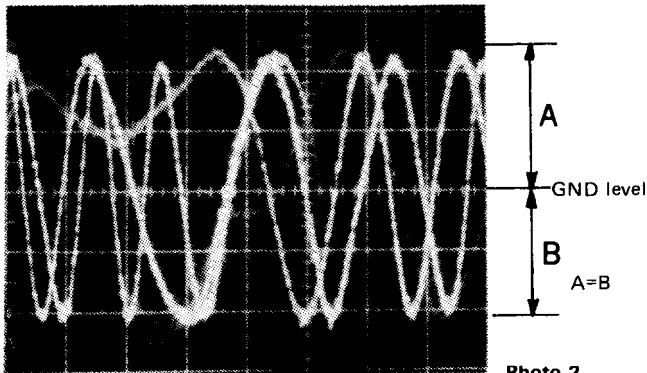
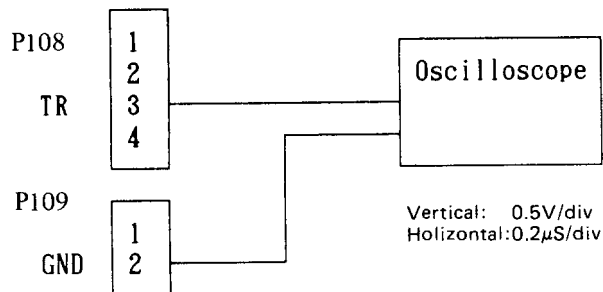


Photo 2



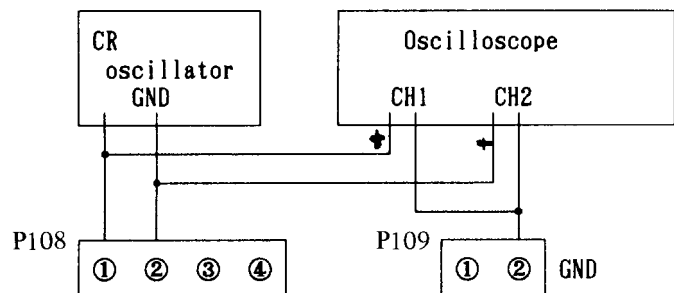
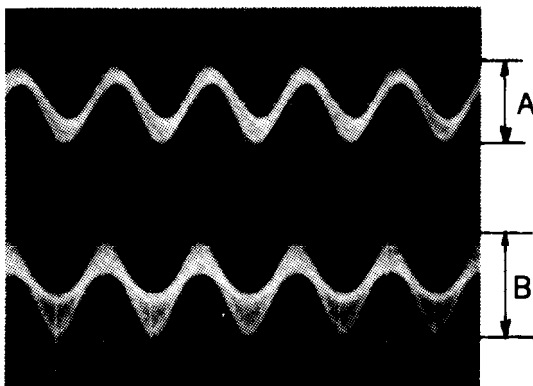
Vertical: 0.5V/div
Horizontal: 0.2μS/div

4. Focus gain adjustment

Set the output of CR oscillator to 800Hz, 1~1.5Vp-p.

Play back the track 2 of test disc.

Connect the oscilloscope and the CR oscillator as shown below.



Vertical : 0.2V/div
Horizontal: 0.5mS/div

Adjust R122 until 800Hz components of CH1 and CH2 on oscilloscope become same level.

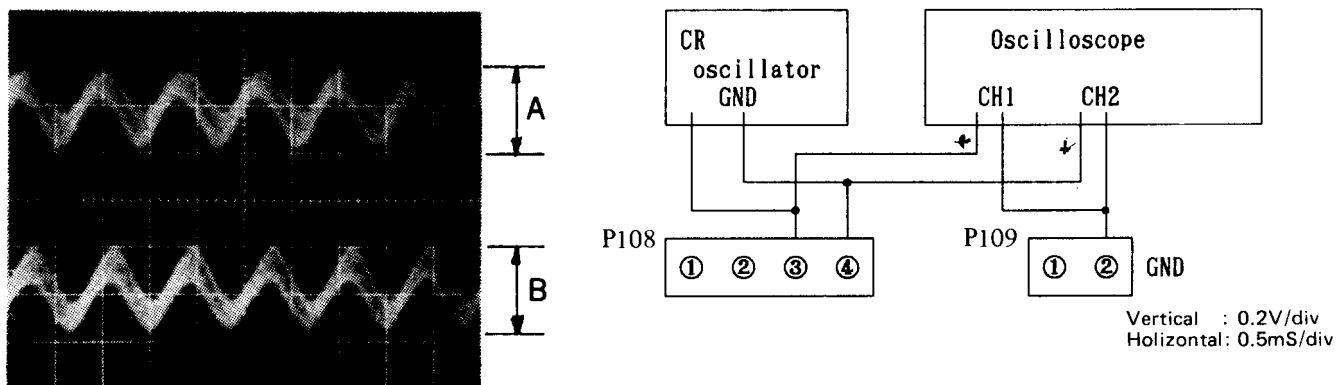
After adjustment, disconnect the CR oscillator and the oscilloscope.

5. Tracking gain adjustment

Set the output of CR oscillator to 1.2kHz, 1~1.5Vp-p.

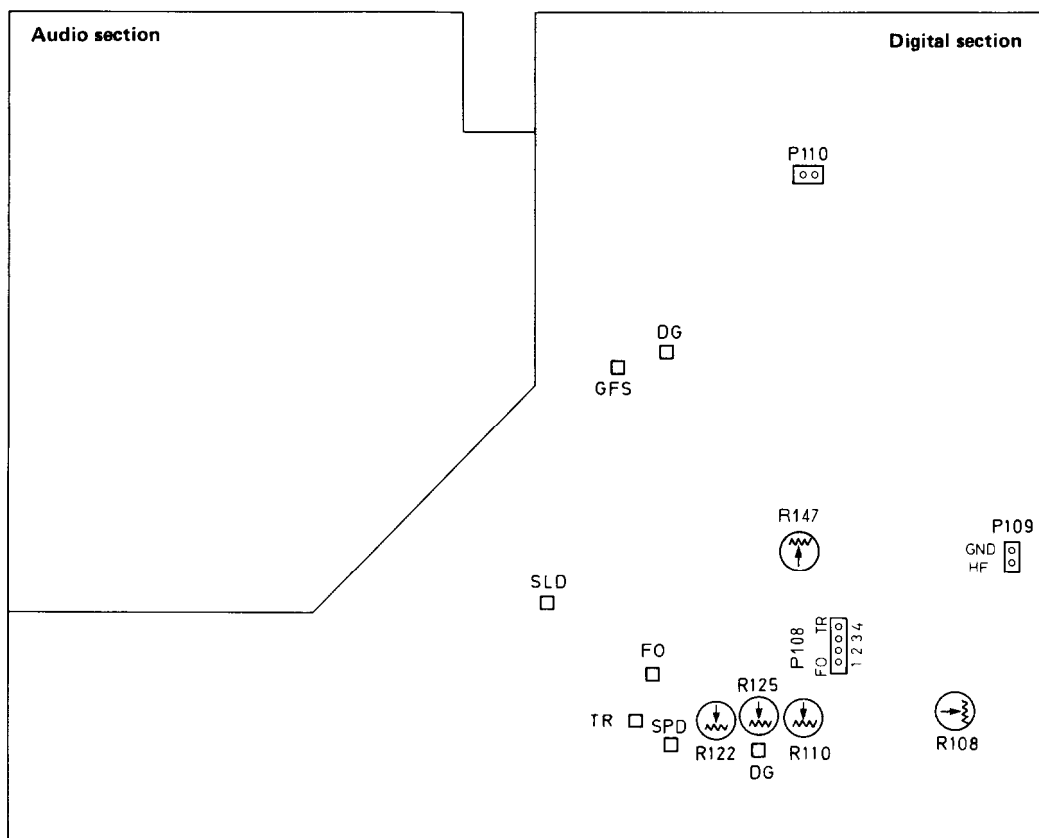
Play back the track 2 of test disc.

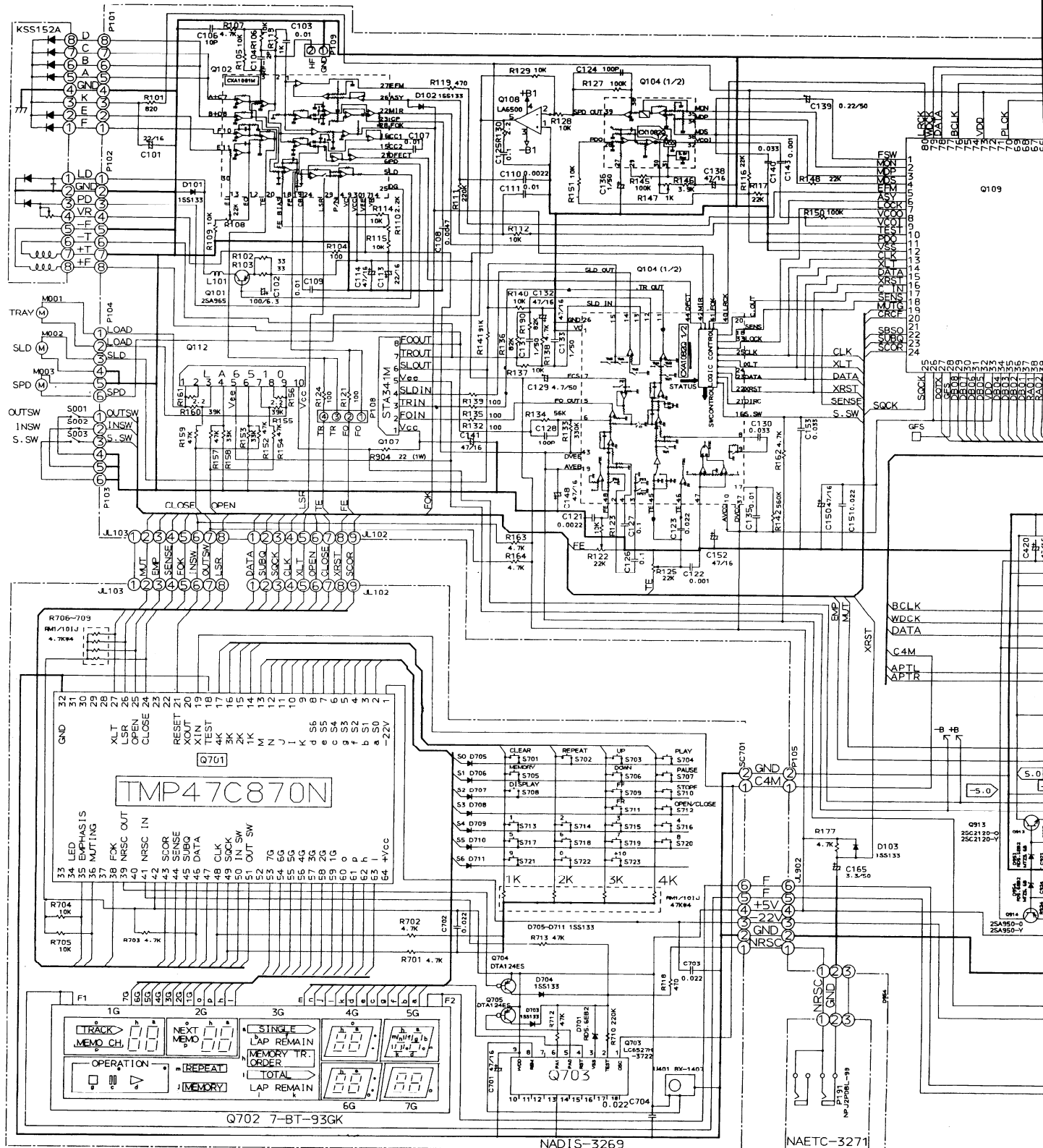
Connect the oscilloscope and the CR oscillator as shown below.



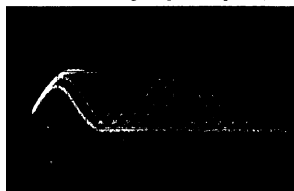
Adjust R125 until 1.2kHz components of CH1 and CH2 on oscilloscope becomes same level.

After adjustment, disconnect the CR oscillator and the oscilloscope.





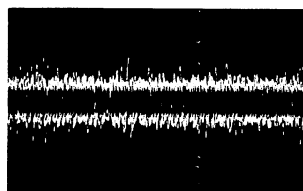
Waveform when play the track 2 of test disc YEDS-18.
Use the high impedance probe(10 : 1)



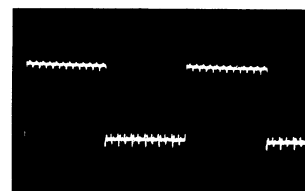
RF signal
P109 Pin2 (HF)
V:50mV/div.
H:0.5 μ s/div.



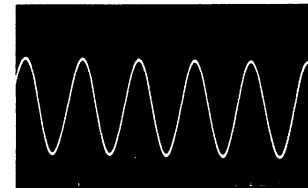
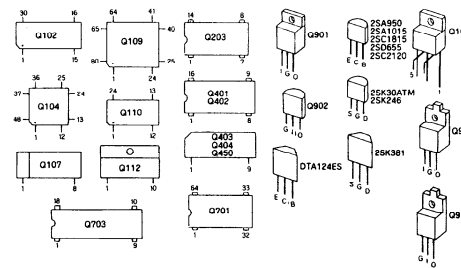
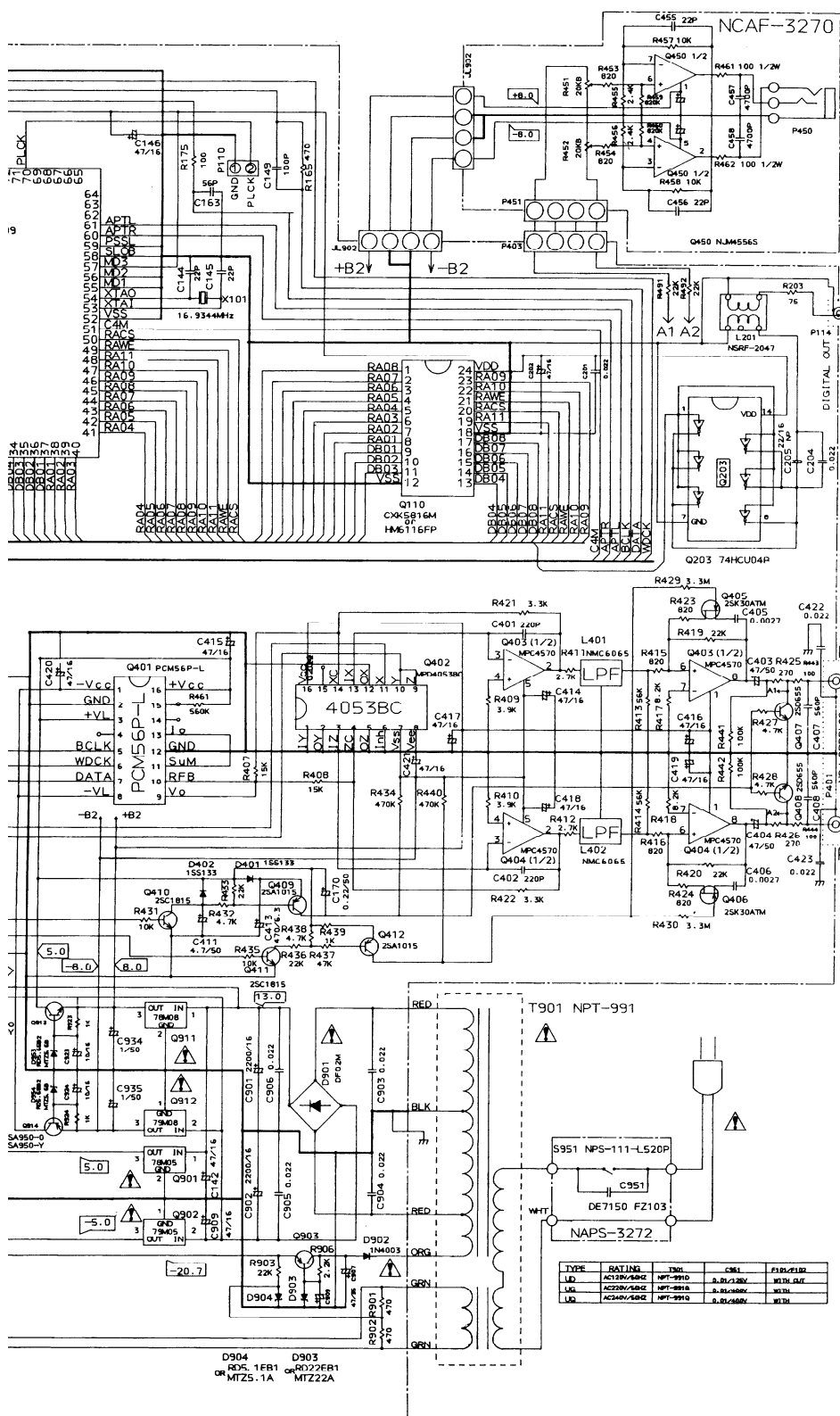
Focusing signal
P108 Pin2
V:10mV/div.
H:0.5ms/div.



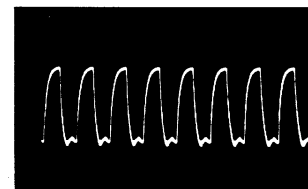
Tracking signal
Q107 Pin3
V:0.1 V/div.
H:0.5ms/div.



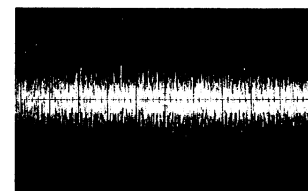
WDCK
Q401 Pin6
V:0.2V/div.
H:1 μ s/div.



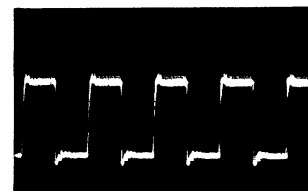
Audio signal
Q403 Pin6
V:50mV/div.
H:0.5ms/div.



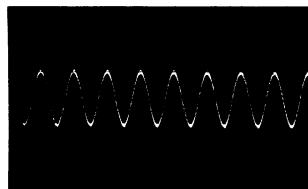
BLCK signal
Q401 Pin5
V:0.2V/div.
H:0.2μs/div.



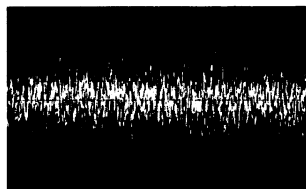
Tracking signal
P108 Pin4
V:20mV/div.
H:0.5ms/div.



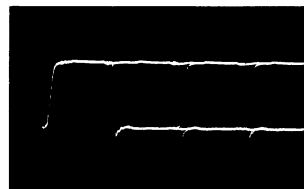
Clock
P110 Pin1 (PLCK)
V:0.2V/div.
H:0.1μs/div.



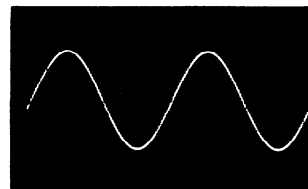
Clock
Q109 Pin53 (C145)
V:0.2V/div.
H:0.1μs/div.



Focusing signal
Q107 Pin2
V:50mV/div.
H:0.5ms/div.



DATA signal
Q401 Pin7
V:0.2V/div.
H:0.1μs/div.



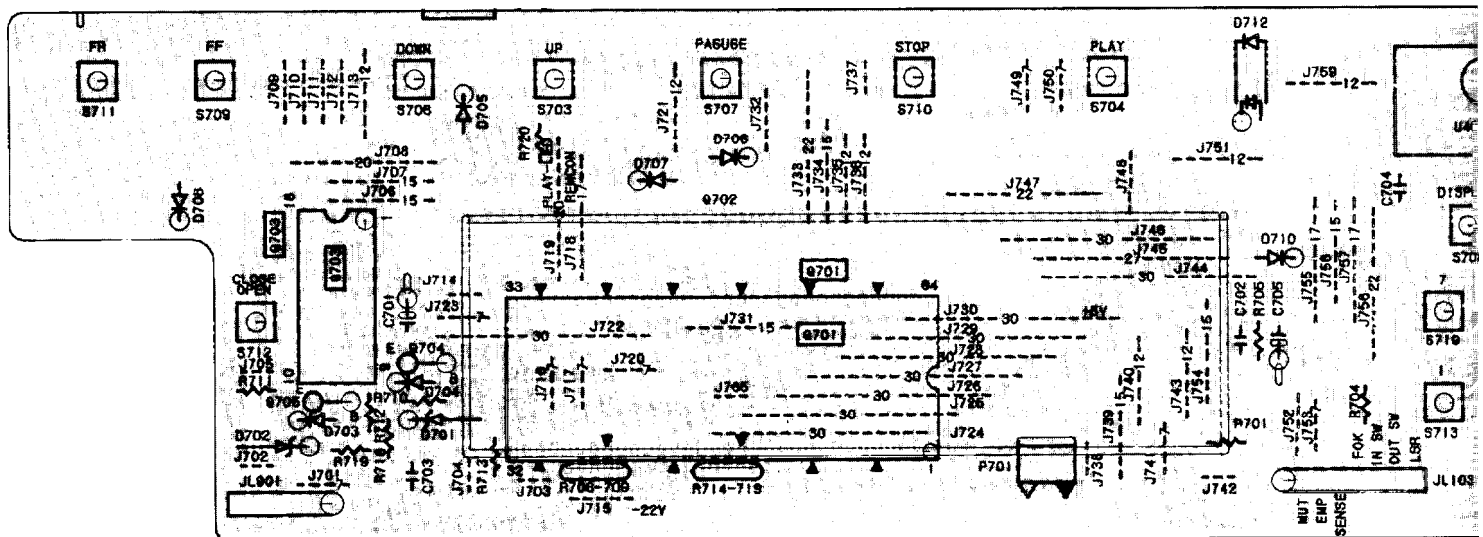
Q401 Pin10
V:0.1V/div.
H:0.2ms/div.

PRINTED CIRCUIT BOARD – PARTS LIST

MAIN CIRCUIT PC BOARD(NAAR-3086-5/5A)

CIRCUIT NO.	PART NO.	DESCRIPTION
ICs		
Q102	22240029	CXA1081M
Q104	22240030	CXA1082AQ
Q107	22240168	STA341M-L
Q108	22240033	LA6500
Q109	22240031	CXD1135Q
Q110	22240142,	CXK5816MS-15,
	222990 or	CXK5816M-15 or
	22240032	LC3517AM-15
Q112	22240034	LA6510
Q203	222755	74HCU04P
Q401	22240096	PCM56P-L
Q402	222840531ROH	BU4053B
Q403,Q404	22240014	μ PC4570HA
Q901	222780052	78M05
Q902	222790053	79L05
Q911	222780085MIT	M5F78M08L
Q912	222790085MIT	M5F79M08L
Transistors		
Q101,Q903	2211503 or	2SA950-O or
Q914	2211504	2SA950-Y
Q405,Q406	2212375	2SK30ATM-GR
Q407,Q408	2211705 or	2SD655-E or
	2211706	2SD655-F
Q409,Q412	2211454 or	2SA1015-Y or
	2211455	2SA1015-GR
Q410,Q411	2211254 or	2SC1815-Y or
	2211255	2SC1815-GR
Q913	2211163 or	2SC2120-O or
	2211164	2SC2120-Y
Diodes		
D101-D103	223163	1SS133
D401,D402	223163	1SS133
D901	223892	DF02M
D902	223880 or	GP101N4003 or
	223896	1N4003F
D903	2239751 or	RD22EB1 or
	2243492	MTZ22A
D904	2239451 or	RD5.1EB1 or
	2243141	MTZ5.1A
D953,D954	2239472 or	RD5.6EB2 or
	2243152	MTZ5.6B
X'tal		
X101	3010112	KD6586FFB
Coils		
L101	231023	NCH1062
L201	232143	NSRF-2047
L401,L402	232141	NMC-6065
Capacitors		
C101,C113	354742209	22 μ F,16V,Elect.
C102	354721019	100 μ F,6.3V,Elect.
C114	354744709	47 μ F,16V,Elect.
C129	354780479	4.7 μ F,50V,Elect.
C132,C138	354744709	47 μ F,16V,Elect.
C133,C136	354780109	1 μ F,50V,Elect.
C139	354781099	0.1 μ F,50V,Elect.
C141,C142	354744709	47 μ F,16V,Elect.
C146,C148	354744709	47 μ F,16V,Elect.
C150,C152	354744709	47 μ F,16V,Elect.
C158,C159	354744709	47 μ F,16V,Elect.
C165	354780339	3.3 μ F,50V,Elect.
C170	352981096	0.1 μ F,50V,Non-polar elect.
C202	354744709	47 μ F,16V,Elect.
C205	352942206	22 μ F,16V,Non-polar elect.
C401,C402	373302214	220pF ± 5%,125V,PP
C416-C419	354744709	47 μ F,16V,Elect.

PRINTED CIRCUIT BOARD VIEW FROM BOTTOM SIDE



DISPLAY CIRCUIT PC BOARD

PRINTED CIRCUIT BOARD-PARTS LIST

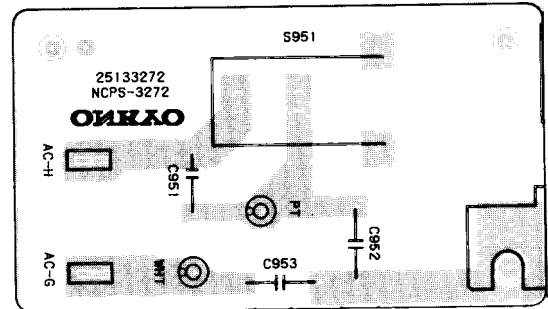
CIRCUIT NO.	PART NO.	DESCRIPTION
C403,C404	392884707	47 μ F,50V,Low-leakage current elect.
C407,C408	373305614	560 pF $\pm$ 5%,125V,PP
C411	354780479	4.7 μ F,50V,Elect.
C413	354724719	470 μ F, 6.3V,Elect.
C414-C421	354744709	47 μ F,16V,Elect.
C901,C902	354742229	2200 μ F,16V,Elect.
C907	354764709	47 μ F,35V,Elect.
C908	354754709	47 μ F,25V,Elect.
C909	354744709	47 μ F,16V,Elect.
C923,C924	354741009	10 μ F,16V,Elect.
C934,C935	354780109	1 μ F,50V,Elect.
R108	5210066	N06HR22KBD,Semi-fixed
R110	5210060	N06HR2.2KBD,Semi-fixed
R122,R125	5210066	N06HR22KBD,Semi-fixed
R147	5210058	N06HR1KBD,Semi-fixed
R904	441622704	27 Ω ,1W,Metal oxide film
P101	25055153	NPLG-9P137
P102	25055152	NPLG-8P136
P103,P104	25055150	NPLG-6P134
P105	25055146	NPLG-2P130
P108	25055045	NPLG-4P33
P109,P110	25055038	NPLG-2P29
P403	25055148	NPLG-4P132
JL102	25050273	NSCT-9P101
JL103	25050272	NSCT-8P100
JL901	25050270	NSCT-6P98
JL902	25050268	NSCT-4P96
P114	25045237	NPJ-1PDOR-111
P401	25045223	NPJ-2PDBL99
27160211-1	RAD68B	
82143006	3P+6FN(BC),Pan head	
F101,F102	252112	ICPN15,IC protector <G>

DISPLAY CIRCUIT PC BOARD(NADIS-3269-1)

CIRCUIT NO.	PART NO.	DESCRIPTION
Q701	22240154	ICs
Q703	22240173	ICs
Q702	212052	Fluorescent tube
Q704,Q705	2212600	Transistors
D701	2239472 or 2243152	Diodes
D703-D711	223163	Diodes
C701	354721019	Capacitor
R706-R709	49163472404	Resistors
R714-R717	49163473404	Resistors
U401	241068	Opto. module
S701-S723	25035548	Switches
SC701	2000872	Socket
	28140825	Cushions
	14 $\times$ 50 $\times$ 15mm	

POWER SWITCH PC BOARD(NAPS-3272-1)

CIRCUIT NO.	PART NO.	DESCRIPTION
C951	3500065A	DE7150FZ103PCSA(400V/125V),Capacitor IS
P951	25035558	NPS-111-L520P,Power switch
	27300601	Cover for C951
	25060092	NTM-IS33,Terminals



CIRCUIT NO.	PART NO.	DESCRIPTION
Q450	222887	NJM4556S,IC
C451,C452	354744709	47 μ F,16V,Elect. capacitors
R451,R452	5104233	N09RGL20KB15F,Variable resistor
R461,R462	442521014	100 Ω , 1/2W,Metal oxide film resistors
P450	25045139	HLJ0540-01-010,Stereo headphone terminal
P451	2000865	NSAS-8P-821,Socket

25133271
NCE1C-3271
04P-20I

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Diagram of NAETC-3360 component layout. The component is a rectangular board with a large central square component. To the left of the central component is a small rectangular component labeled "To JLI01". To the right of the central component is a long rectangular component labeled "To Q115". Below the central component is another long rectangular component labeled "To JLI01".

NAETC-3360

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BLOCK DIAGRAM

